

# **[LAMINATION PROCESS OF PACKAGING SUBSTRATE]**

## **Abstract of Disclosure**

In a lamination process, a plurality of substrate layers are stacked on one another, a topmost substrate layer having an opening therein. A fill material is formed under liquid form in the opening, and is solidified. Thereafter, the substrate layers are heated and pressed between two pressing plates in a press-bonding process, the fill material receiving a pressure of the pressing plates. The pressing plates have planar pressing surfaces, which therefore prevents alteration of the cavity shape and size.

## Figures